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# The effect of boron on the electronic structure of grain boundaries in Ni<sub>3</sub>Al

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**Abstract.** The electronic structure of  $\Sigma 5[001](210)$  and  $\Sigma 13[001](320)$  grain boundaries in Ni<sub>3</sub>Al containing B are investigated by the use of the discrete variational method. The effects of B on Ni<sub>3</sub>Al grain boundaries are discussed. The results show that B forms stronger bonding states with its neighbouring host atoms, and it can be expected that the cohesive strength of the grain boundaries will be increased.

## 1. Introduction

Grain boundaries are important defects in materials; they are closely tied in with the properties of alloys. Studies of the effects of impurities (such as B, C, S, P and H) on the embrittlement of metal and intermetallic compounds provide the foundation for increasing the strength levels of materials. There have been some experimental and theoretical studies in this field; the polyhedral cluster model has been used to represent the local environment of grain boundaries doped with impurities and to study the electronic structure of materials containing structural defects [1–5]. Messmer and Briant [1, 2] reported the effect of the doping in the grain boundaries on the features of bonding. Their results showed that if boron is in the interstices of a nickel grain boundary, in addition to the charge in the metal bonds across the grain boundary not decreasing, a covalent-like bond is formed between the boron and the host metal. This bonding will give additional cohesiveness across the grain boundary. Hashimoto et al [6] and Wang and Zhao [7], using the recursion method, studied the action of the B and P in grain boundaries of Fe, and B, N and P in grain boundaries of Ni respectively; the results are similar to Messmer's. Goodwin et al [8] and Needels et al [9], using the pseudopotential total energy technique, calculated the interlayer cohesive energy of Al and the total energy of grain boundaries for Au. With the rapid development of computer technology, one can study the electronic structure of grain boundaries in a larger cluster or embedded cluster from first principles. Recently, Tang, Freeman and Olson used the DMol method [10] to study the electronic structure of B and S/Fe  $\Sigma$ 3 grain boundaries, and provided useful information revealing the nature of the embrittlement for the Fe  $\Sigma 3$ grain boundary.

 $Ni_3Al$  with the  $L1_2$  structure is ductile as a single crystal, but it is intergranularly brittle in the polycrystalline state [11]. It is found that the brittleness of grain boundaries in  $Ni_3Al$ 

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is intrinsic [11]. However, when the intermetallic compound Ni<sub>3</sub>Al is doped with a small amount of boron the tendency towards intergranular fracture is reduced significantly [12]. Two mechanisms were proposed to explain how the segregation of boron at grain boundaries improves the ductility. One of these is that B segregated at grain boundaries will increase the cohesive strength of the grain boundaries by the formation of strong metallic bonds [13, 14]. The other is that B segregated at grain boundaries reduces atomic ordering in the grain boundary regions and this results in the increase of the mobility of dislocations in grain boundaries [15, 16], or of the number of available dislocation reactions at the grain boundaries [17], or both [18]. Whether or not this mechanism successfully explains the effect of B on Ni<sub>3</sub>Al grain boundaries has not been decided as yet.

Chaki proposed a model for explaining the effect of boron on the ductility of Ni-rich Ni<sub>3</sub>Al [19, 20]. It is argued that the interstitial boron and antisite Ni atoms distort bonds and reduce the directionality or the strength of Ni–Al bonds in the interior of the grains in Ni<sub>3</sub>Al. This makes generation and propagation of dislocations easier in the grains. Chen *et al*, using atomistic simulations, studied the structure of Ni<sub>3</sub>Al grain boundaries [21] and the effects of boron on Ni<sub>3</sub>Al grain boundaries [22]. Their results showed that boron is found to segregate more strongly to grain boundaries than to free surfaces, and the boron segregation at grain boundaries will increase the grain boundary cohesive strength. In addition, Eberhart and Vvedensky calculated the density of states of Ni<sub>3</sub>Al grain boundaries using a multiple-scattering (MS)  $X_{\alpha}$  method with a small cluster [5]. Their calculated result showed that the appearance of localized grain boundary states near the Fermi level is an indicator that a compound is prone to intergranular fracture, and indicated that the mechanical stability of the grain boundary is decreased compared to that of the parent crystal of Ni<sub>3</sub>Al.

In this paper, the discrete variational (DV) method [23–26] within the framework of density functional theory is used to study the effect of boron on  $Ni_3Al$  grain boundaries. The methodology and the model are presented in section 2, the calculated results are discussed in section 3, and we give some conclusions in the last section.

## 2. The computation method and cluster model

The discrete variational method (DVM) which is a first-principles numerical method for solving the local density functional equations [23–26] is used to study the electronic structure of grain boundaries in Ni<sub>3</sub>Al and the effect of boron. In this paper, the embedded-cluster approach is used, and the charge density of several hundreds of atoms surrounding the grain boundary is considered in constructing the self-consistent potential.

In the one-electron-like wave equation, the Hamiltonian is

$$H = -\nabla^2/2 + V_c + V_{xc} \tag{1}$$

where  $V_c$  is the electron–nucleus and electron–electron Coulomb potential, and  $V_{xc}$  derived by Von Barth and Hedin [27] is the exchange–correlation potential. The eigenstates (or molecular orbitals) are expanded as linear combinations of atomic orbitals  $\phi_i(r)$  [26]:

$$\Psi_n(r) = \sum_i C_{ni} \phi_i(r).$$
<sup>(2)</sup>

In order to study the interaction between atoms, the interatomic energy between atom l and atom m is derived [7, 28]:

$$E_{lm} = \sum_{n} \sum_{\alpha\beta} N_n a^{\star}_{n\alpha l} a_{n\beta m} H_{\beta m\alpha l}$$
(3)

where  $N_n$  is the occupation number for molecular orbital  $\Psi_n$ ,  $a_{n\alpha l} = \langle \phi_{\alpha l}(r) | \Psi_n(r) \rangle$ , and  $H_{\beta m\alpha l}$  is the Hamiltonian matrix element connecting the atomic orbital  $\beta$  of atom *m* and the atomic orbital  $\alpha$  of atom *l*.

In the computation, the single-site orbitals are used as the basis set, and the frozen-core mode is chosen; also the funnel potential is introduced. The non-spin-polarized secular equations are solved using the self-consistent-charge (SCC) approximation.



**Figure 1.** The atomic configurations around tilt grain boundaries in Ni<sub>3</sub>Al. The Ni and Al atoms are represented by the circles and squares; the different sizes represent different layers. The atoms shown as solid symbols and labelled by numbers are in the cluster; the solid diamonds represent the B atom. (a)  $\Sigma$ 5[001](210); (b)  $\Sigma$ 13[001](320).

The grain boundaries  $\Sigma 5[001](210)$  and  $\Sigma 13[001](320)$ , which are constructed by use of the coincidence site lattice model [29, 30] and atomistic simulations [21], are investigated. Figures 1(a) and 1(b) show the atomic configurations for  $\Sigma 5$  and  $\Sigma 13$  grain boundaries. The cluster atoms shown as solid symbols (in figure 1) are embedded in several hundreds of surrounding atoms. In order to discuss the interaction between atoms clearly, the atoms in the cluster are labelled with numbers. With a method like that of Masuda-Jindo [31], the atomic relaxation is carried out by the energy-minimization procedure in which a proportion of the atoms at grain boundaries are pulled apart from the interface. When the minimum of the binding energy is achieved for the cluster system, the equilibrium configuration is given.



**Figure 2.** The charge-density difference between the B-doped grain boundary and a superposition of a single B atom and clean grain boundary, (a) and (b) for  $\Sigma 5[001](210)$ , and (c) and (d) for  $\Sigma 13[001](320)$  tilt grain boundaries in Ni<sub>3</sub>Al. The contour spacings are 0.001*e* au<sup>-3</sup>. Solid lines indicate a gain of charge and dashed lines indicate a loss of charge.

## 3. Results and discussion

#### 3.1. Charge density

The charge-density difference is obtained by subtracting the charge density of the clean grain boundary and a free boron atom from the charge density of the B-doped grain boundary. So that the boron-induced charge redistribution can be seen more clearly [10], we show in figure 2 the charge-density difference plotted in the Y-Z plane which contains nickel atoms and boron, and the X-Y plane which contains Ni<sub>2</sub>, Ni<sub>3</sub>, Ni<sub>4</sub> and Ni<sub>5</sub> atoms and is near to the boron.

In figure 2, it can be seen that the charge density in the intermediate region between boron and its near-neighbour atoms is obviously increased, but the charge density between Ni<sub>2</sub> and Ni<sub>3</sub> (or Ni<sub>4</sub> and Ni<sub>5</sub>) host atoms (these pairs of atoms are across the grain boundaries) is hardly affected by the boron. This is similar to the behaviour of boron in the B-doped nickel grain boundaries [1, 2]. The results for  $\Sigma 5$  and  $\Sigma 13$  grain boundaries indicate that boron forms relatively strong bonds with its neighbouring atoms. Thus this can be regarded as the B atom acting as a 'bridge' and increasing the cohesive strength of the grain boundaries. The above calculated results are in agreement with the atomistic simulation study [22]. Meanwhile, from the calculation of the charge-density difference it can also be found that the effect of boron on the host atoms is localized in the region near to the boron. The feature is also found in the B/Fe  $\Sigma$ 3 grain boundary system [10].

**Table 1.** The interatomic energies (in eV) of the adjacent atoms in grain boundaries with  $(E_{GB+B})$  and without  $(E_{GB})$  B atoms;  $\Delta E = E_{GB+B} - E_{GB}$  is the change of interatomic energy induced by the addition of a B atom.

Pairs of		Σ5		Σ13			
atoms	$E_{GB}$	$E_{GB+B}$	$\Delta E$	$E_{GB}$	$E_{GB+B}$	$\Delta E$	
Ni <sub>1</sub> -Ni <sub>2</sub>	-1.399	-1.176	0.223	-1.447	-1.223	0.224	
Ni <sub>2</sub> -Ni <sub>3</sub>	-4.048	-3.649	0.399	-3.091	-2.932	0.159	
Ni <sub>1</sub> -Al <sub>6</sub>	-1.263	-1.279	-0.016	-1.441	-1.488	-0.047	
Ni <sub>1</sub> -Ni <sub>12</sub>	-1.232	-1.222	-0.010	-1.479	-1.534	-0.055	

**Table 2.** The interatomic energies  $E_{B-l}$  (in eV) between the B atom and its adjacent atoms.

		Σ5				Σ13				
	B-Ni <sub>1</sub>	B-Ni <sub>2</sub>	B-Ni <sub>14</sub>	B-Al <sub>18</sub>	B-Ni <sub>1</sub>	B-Ni <sub>2</sub>	B-Ni <sub>19</sub>	B-Al <sub>21</sub>		
$E_{B-l}$	-2.477	-2.326	-2.892	-0.747	-2.608	-2.009	-2.962	-1.044		

#### 3.2. Interatomic energy

The interatomic energies defined by equation (3) are calculated, and the results are listed in tables 1 and 2. From table 1, we can find that the energy of interaction between host atoms which are close to B atoms, such as the pairs of  $Ni_1-Ni_2$  and  $Ni_2-Ni_3$ , is weakened by the addition of B atoms. However, the energy of interaction between host atoms which are not near B atoms, such as  $Ni_1-Al_6$  and  $Ni_1-Ni_{12}$  pairs, is slightly changed by the addition of B.

From table 2, it can be seen that the energy of interaction between boron and its neighbouring atoms is very strong; this is closely related to the cohesion of the grain boundary, and is consistent with the calculated results for the charge density. On the basis of the calculation of the interatomic energy, it can be predicted that the B atom will enhance the grain boundary and thus inhibit intergranular fracture. The theoretical results from first-principles numerical calculations are in agreement with the experimental results [13] and the atomistic simulation study [22]. In addition, our calculated results also show that the bonding formed by boron with nickel is very strong, and that the interaction between Ni and Al ( $E_{Ni_1-Al_6}$ ) is not decreased by the addition of B atoms. This is at variance with Chaki's suggestion that the interstitial B atoms in Ni-rich Ni<sub>3</sub>Al reduce the strength of the directional bonding between Ni and Al atoms in the interior of the grains [20].

In order to discuss the influence of the deviation from stoichiometric composition on the ductility of B-doped Ni<sub>3</sub>Al alloy, the interatomic energies of several other clusters belonging

to the  $\Sigma 5$  and  $\Sigma 13$  grain boundaries are calculated. One typical cluster is shown in figure 4, in which the centre of the cluster is translated from the Ni<sub>1</sub> atom to the Al<sub>16</sub> atom associated with figure 1(a). The typical interatomic energies for the boron and Ni atoms from the  $\Sigma 5$  grain boundary shown in figure 1(a) are assigned as  $E_{B-Ni_1} = -2.477$  eV and  $E_{B-Ni_{14}} = -2.892$  eV, and the corresponding interatomic energies in the other  $\Sigma 5$  cluster shown in figure 4 are  $E'_{B-Al_1} = -2.124$  eV and  $E'_{B-Al_{14}} = -2.413$  eV respectively. The results indicate that the interaction between B and Ni is stronger than that between B and Al, and so the B atom tends to interact with Ni atoms rather than with Al atoms. Therefore it can be predicted that the amount of boron segregated to the grain boundary will be decreased with the increase of aluminium concentration in Ni<sub>3</sub>Al, and that the effect of boron on the ductility of Ni<sub>3</sub>Al will become less when the content of boron is less than the critical amount at the grain boundary [13].



**Figure 3.** The partial densities of states (PDOS) of a B atom and its neighbouring atoms for (a)  $\Sigma 5(210)$  and (b)  $\Sigma 13(320)$  tilt grain boundaries in Ni<sub>3</sub>Al. The solid and broken lines represent the PDOS of doped and clean grain boundaries respectively.

### 4. Density of states

The densities of states (DOS) are obtained by broadening the discrete eigenvalue spectrum with a set of Lorentz functions. The partial densities of states (PDOS) of a B atom and its neighbouring Ni atoms are shown in figure 3. Comparing the DOS of a B-doped grain boundary with that of a clean grain boundary, some features can be noted. First, the s and d PDOS of the host atoms are moved towards deep potential wells with the addition of B. Second, a hybridization between B sp and Ni sd takes place. However, the p PDOS of host



Figure 4. The calculated atomic configuration of another cluster which belongs in the  $\Sigma 5[001](210)$  tilt grain boundary in Ni<sub>3</sub>Al. The meaning of the symbols is the same as in figure 1.

atoms are hardly affected by the addition of B. From the point of view of energetics, this can be regarded as B making the grain boundary more stable and enhancing the cohesion of the grain boundary. In addition, it can be found that the changes of the DOS near the Fermi level induced by the addition of B arise mainly from changes of the d PDOS, while the s and p PDOS are almost unchanged. The reduction of the DOS near the Fermi level means that the transition probability of electronic states is confined; thus the addition of B may be beneficial to the stability of grain boundaries. This is consistent with the (MS)  $X_{\alpha}$  calculation [5].

**Table 3.** The electron occupation number *n* in valence orbitals and the changes  $(\Delta n = n(\text{GB} + \text{B}) - n(\text{GB}))$  induced by the addition of a B atom.

		Ni1			Ni <sub>2</sub>			Ni <sub>14</sub> (Ni <sub>19</sub> )		
		3d	4s	4p	3d	4s	4p	3d	4s	4p
Σ5	n(GB) n(GB+B) $\Delta n$	8.368 8.396 0.028	0.738 0.728 -0.010	0.542 0.597 0.055	8.227 8.240 0.013	0.959 0.934 -0.025	0.857 0.931 0.074	8.211 8.226 0.015	1.098 1.037 -0.061	0.767 0.870 0.103
Σ13	n(GB) n(GB+B) $\Delta n$	8.372 8.388 0.016	$0.764 \\ 0.742 \\ -0.022$	0.609 0.711 0.102	8.251 8.266 0.015	1.041 0.990 -0.051	0.762 0.838 0.076	8.246 8.251 0.005	1.171 1.105 -0.066	0.589 0.730 0.141

The electron occupation number of orbits is calculated by use of Mulliken analysis; the results are presented in table 3. From the calculated results, it can be seen that the number of electrons in 4s orbitals of host Ni atoms decreases with the addition of B, while the numbers of electrons in 3d and 4p orbitals increase. The weakening of the directional bonding states formed by p and d orbitals may be related to the characteristic of fracture of the grain boundary and reflects the boron being a cohesion enhancer.

### 5. Conclusion

We have performed a first-principles numerical calculation to study the effect of B on the grain boundaries in  $Ni_3Al$ . It is found that a strong bonding between B and the host atoms is formed, and that the B–Ni bonding strength is larger than that for B–Al. This suggests that the B will 'prefer' to segregate at Ni-rich grain boundaries, rather than stoichiometric or Al-rich boundaries. On the other hand, the addition of boron results in the DOS shifting

towards the deep energy region and reduces the DOS near the Fermi level; this is a mark of the stability of the system. It can be concluded that as a cohesion enhancer, B segregated at grain boundaries will improve the ductility of polycrystalline  $Ni_3Al$  in Ni-rich cases.

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